

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	XDPL8105	**Issued**	1. August 2018
MA#	MA001641288		
Package	PG-DSO-8-58	**Weight***	81.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.789	2.19	2.19	21931	21931
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.035	0.04		432	
	non noble metal	iron	7439-89-6	0.705	0.86		8641	
	non noble metal	copper	7440-50-8	28.624	35.09	36.00	350851	360032
wire	noble metal	palladium	7440-05-3	0.000	0.00		6	
	non noble metal	copper	7440-50-8	0.046	0.06	0.06	558	564
encapsulation	organic material	carbon black	1333-86-4	0.146	0.18		1793	
	plastics	epoxy resin	-	4.731	5.80		57987	
	inorganic material	silicondioxide	60676-86-0	43.894	53.81	59.79	538027	597807
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	9975	9975
plating	noble metal	silver	7440-22-4	0.084	0.10	0.10	1034	1034
glue	plastics	acrylic resin	-	0.141	0.17		1731	
	noble metal	silver	7440-22-4	0.565	0.69	0.86	6926	8657
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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